



Update from UH: Precision Timing and Continuous Acquisition Pixels

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Mini-Trig/DAQ Workshop
November 2003
@Nara

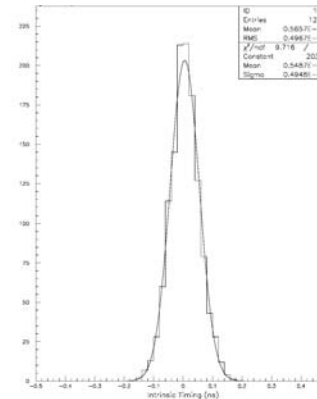
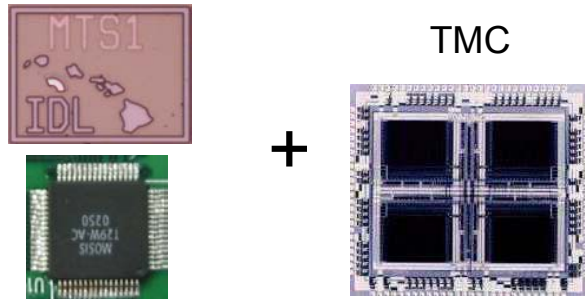


奈良女子大学

Nara Women's University

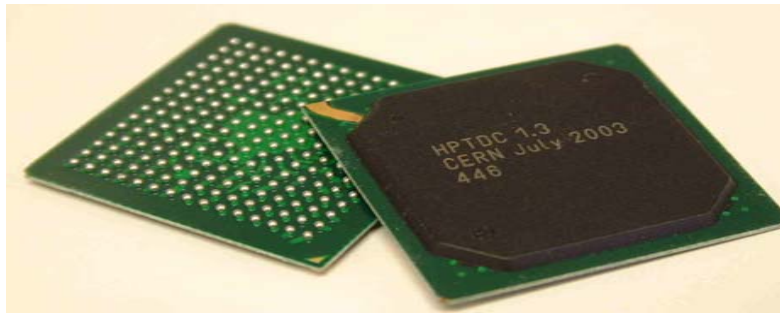
Precision Timing Update

- Two viable techniques:

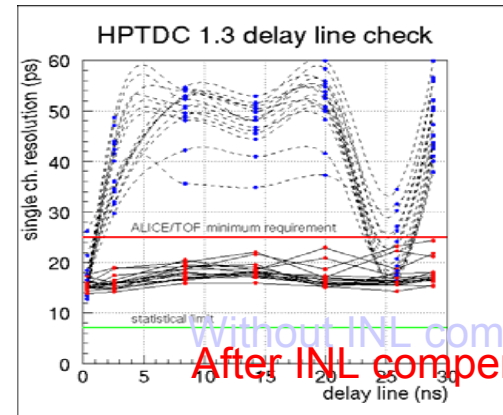


$\sigma \sim 25\text{ps}$
(system subtracted)

Both require calibration for high precision performance



Measurements from ALICE-TOF



- Both options are possible
 - Cost benefit to HPTDC solution (<\$8/channel)



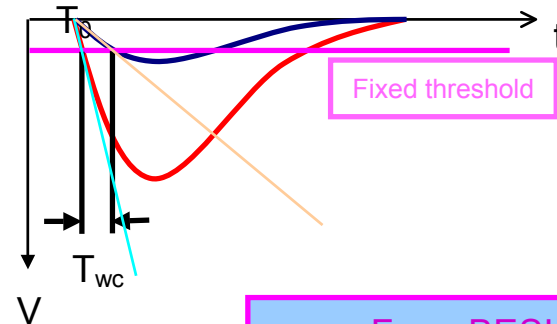
TDC Comparison

- MTS + TMC Benefits:
 - We control the design
 - Separate TS and TDC clocks
- MTS + TMC Negatives:
 - 2 chips
 - More expensive
 - Less well tested (many users, CERN evaluation)
 - MTS1 must be ported (competing with pixel effort)
- HPTDC Negatives:
 - Production order “lifetime buy” in 2004
 - Still a few bugs
 - Complexity: many, many registers...



PID Concerns

- Concern about discriminators
- Our old nemesis, TWC
- Not tightly coupled to detector R&D
- No idea about barrel channel count



From BESIII
Workshop June, 2002
Applies to high resolution
TOF proposal

	Belle		BESIII	
	Spec.	guess?	Spec.	
RF/BCO	<35 ps	35 ps	<35 ps	
uncorrected t=0		?	?	within run
Discrim. Overdrive		?	?	could be calibrated
Beam bunch length	2.5 mm	8.3 ps	50 ps	15 mm
Time Encoding	<20ps	22 ps	?	
		(~42 ps)		
TOTAL	< 40 ps	~45 ps	<u>< 45 ps ?</u>	looks difficult

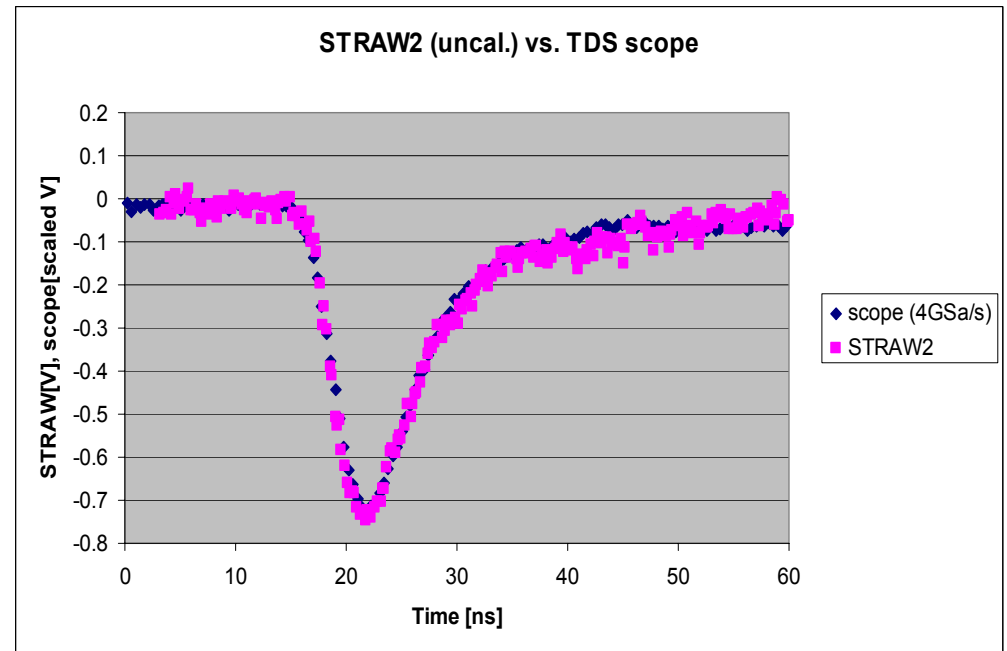
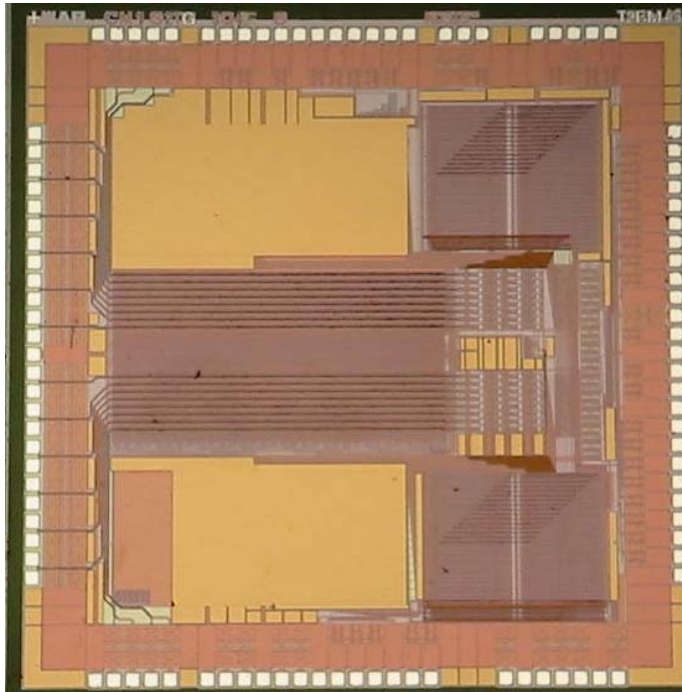
- GEANT/full simulator contribution:

$$\sigma_{fin}^2 \rightarrow 100\text{ps} - \text{“known”} \sim \text{“physics”} \rightarrow 40\text{ps}$$



Waveform Sampling

- Looks very promising:



- GHz analog bandwidth, multi- GSa/s – depth issue
- Will keep in my back pocket...



2004 FINESSE Efforts

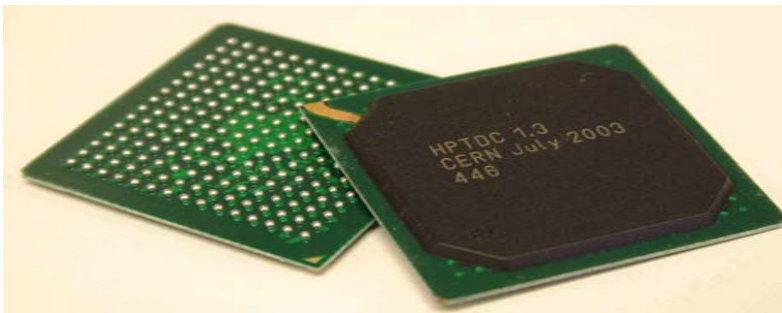
- CuEval2



(Migrate to COPPER2)

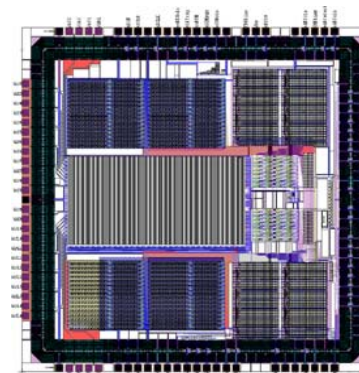
[Belle Note "soon"]

- HPTDC (10 samples)

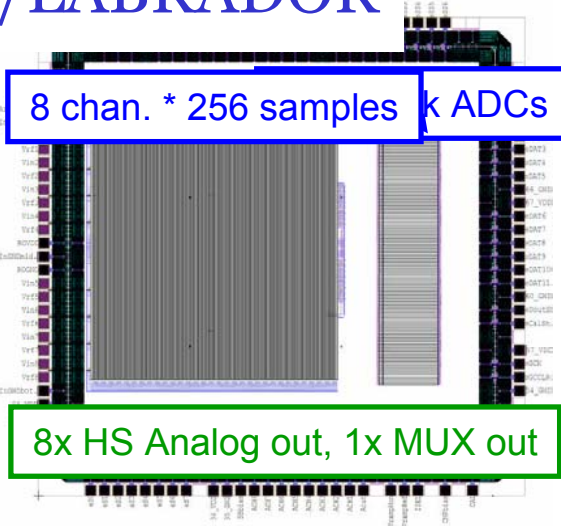


- Precise RF clock avail.?

- STRAW₃/LABRADOR



STRAW3



- Need a stable COPPER

Momentum Toward APS upgrade

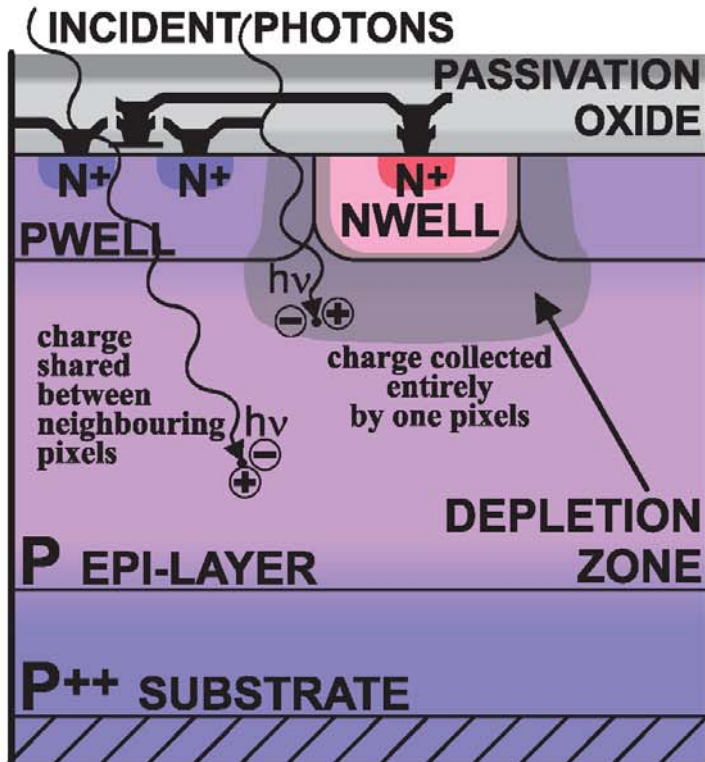
- There has been much Active Pixel Sensor progress recently:
 - LEPSI/TESLA(MIMOSA) & LBNL/STAR prototypes
 - Hawaii has been evaluating STAR prototype
 - RAL (APV25) also getting into the act
 - Hawaii is fabricating 2 protos (CAP1,CAP2) for B-factory
 - Will explain more about today
 - Beam test of Belle pixel proto sometime next year
 - For use in Belle/Super-Belle, some implications for DAQ
 - Maximum readout latency? (pipelined)
 - Trade-off of latency vs. compression
 - In the spirit of “adiabatic” improvements, we may not have to wait for Super-B shutdown to replace SVD2 L1 with pixels – but not if DAQ can't handle it



A Truly Attractive Proposition

CMOS Monolithic Active Pixel Sensors (MAPS) principle

“From digital cameras to particle tracking device”



- The active volume (epi-layer, $\sim 10 \mu\text{m}$ thick) is underneath the readout electronics, providing 100% fill factor

- The charge generated by ionization is collected by the n-well/p-epi diode

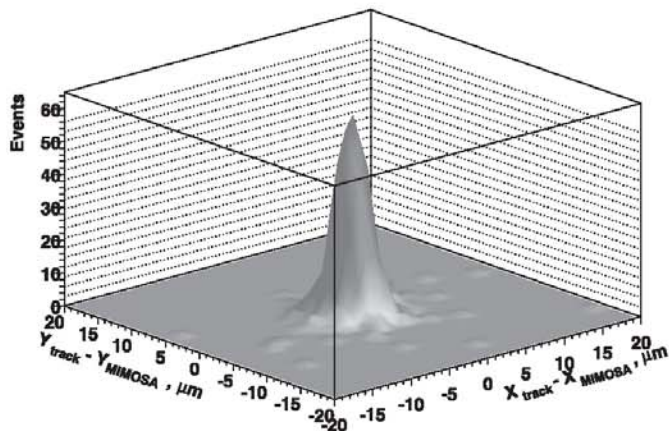
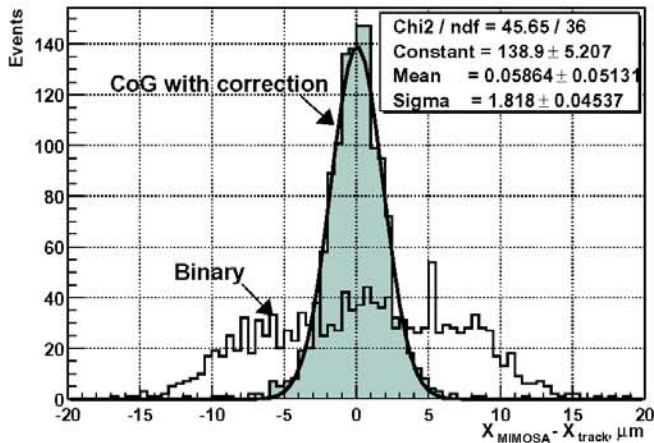
- Charge collection is achieved by the thermal diffusion

The device can be fabricated using a **standard, cost effective and easily available twin-tub CMOS process on epi substrate. No post-processing (e.g. bump-bonding)!**

System-on a chip approach possible

Promising Results

CMOS MAPS particle tracking performance (20 μm pitch)



ENC \sim 10 electrons: $S/N > 30$
Efficiency (5 σ seed cut): $\epsilon_{\text{MIP}} > 99\%$
Spatial resolution: $\sigma = 1.4 \mu\text{m}$

Demonstrated on several devices in various submicron CMOS processes:

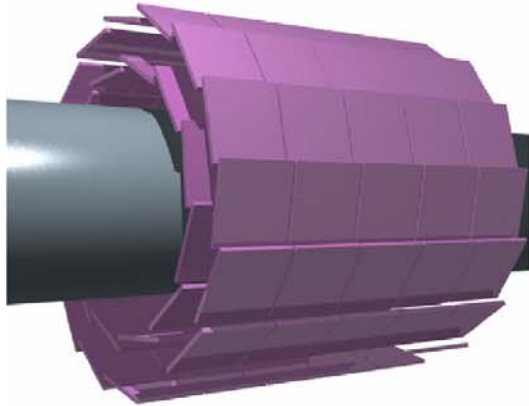
AMS 0.6 μm , 14 μm epi
Alcatel 0.35 μm , 4 μm api
AMS 0.35 μm , no(!) epi

...

TSMC 0.25 μm , 8 μm epi
(LBL team)

+UH,
RAL

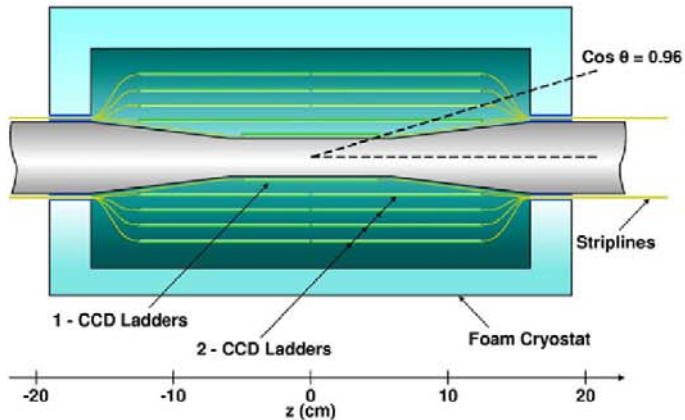
Other Experiments Considering



STAR μ vertex detector

1. First upgrade (x4 present luminosity, 2006):
10 – 20 ms readout (integration) time
2. Second upgrade (x40 present luminosity, 2008):
2 – 5 ms readout (integration) time

Super-Belle: $10\mu\text{s}$?



TESLA Vertex Detector*

1. Outer layers readout time: 100 -200 μs
2. Innermost layer readout time: 25 -50 μs

*NLC/JLC: $t \sim 10$ ms

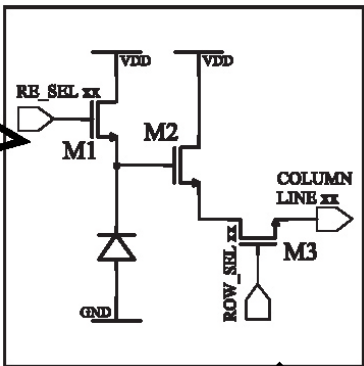


Continuous Acquisition Pixel

- Conceptually Simple

- Analog reset, sample & then sample continuously
- Row-wise analog shift out as fast as possible:

- Consider $22.5\mu\text{m}$ pitch output w/ 4:1 AMUX
- 100MSa/s output (e.g. 8-bit ADC on output)
- $10\mu\text{s}$ for 1k columns (# row independent)
- Possibility of passing signals through to allow joining to form ladders

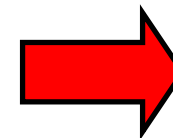


Standard APS pixel

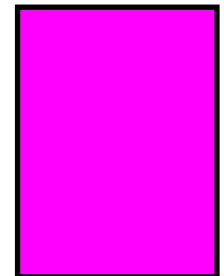


Pixel Array: Column select – ganged row read

High-speed



analog



& storage

Low power – only significant draw at readout edge



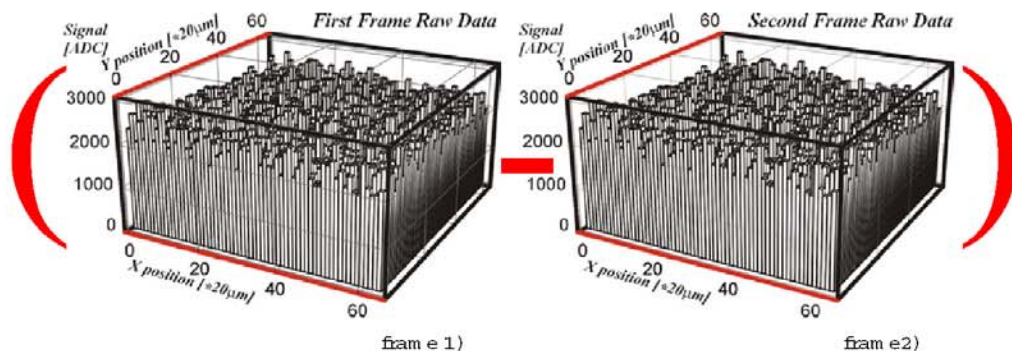
CAP1 Concept

- Automatic CDS
 - When receive L1 trigger:
 - * sift data in sync pipe and provide the difference in value for orbit with trigger and preceding orbit
 - Analog reset
 - If can reset once every 100 orbits, 1% “deadtime”
 - $1\mu\text{s}$ “reset” and $10\mu\text{s}$ to obtain a baseline sample
 - Possibly even less, depending upon dynamic range and background
 - Can build “intelligence” into reset
 - When starting to saturate
 - L1 busy
 - Minimization of leakage current important
 - Relatively simple to fabricate



Correlated Double Sampling

Data processing: (Digital) Correlated Double Sampling

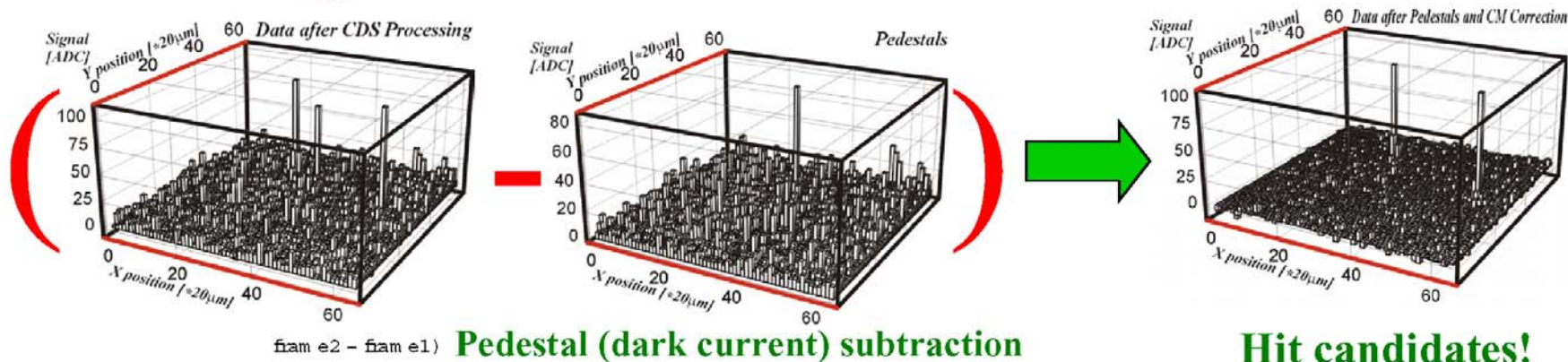


Useful signal on top of
Fixed Pattern DC level

Fixed Pattern dispersion: ~ 100 mV

Typical signal amplitude: ~ 1 mV

(frame2 - frame1) subtraction



fram e2 - fram e1) Pedestal (dark current) subtraction

Hit candidates!

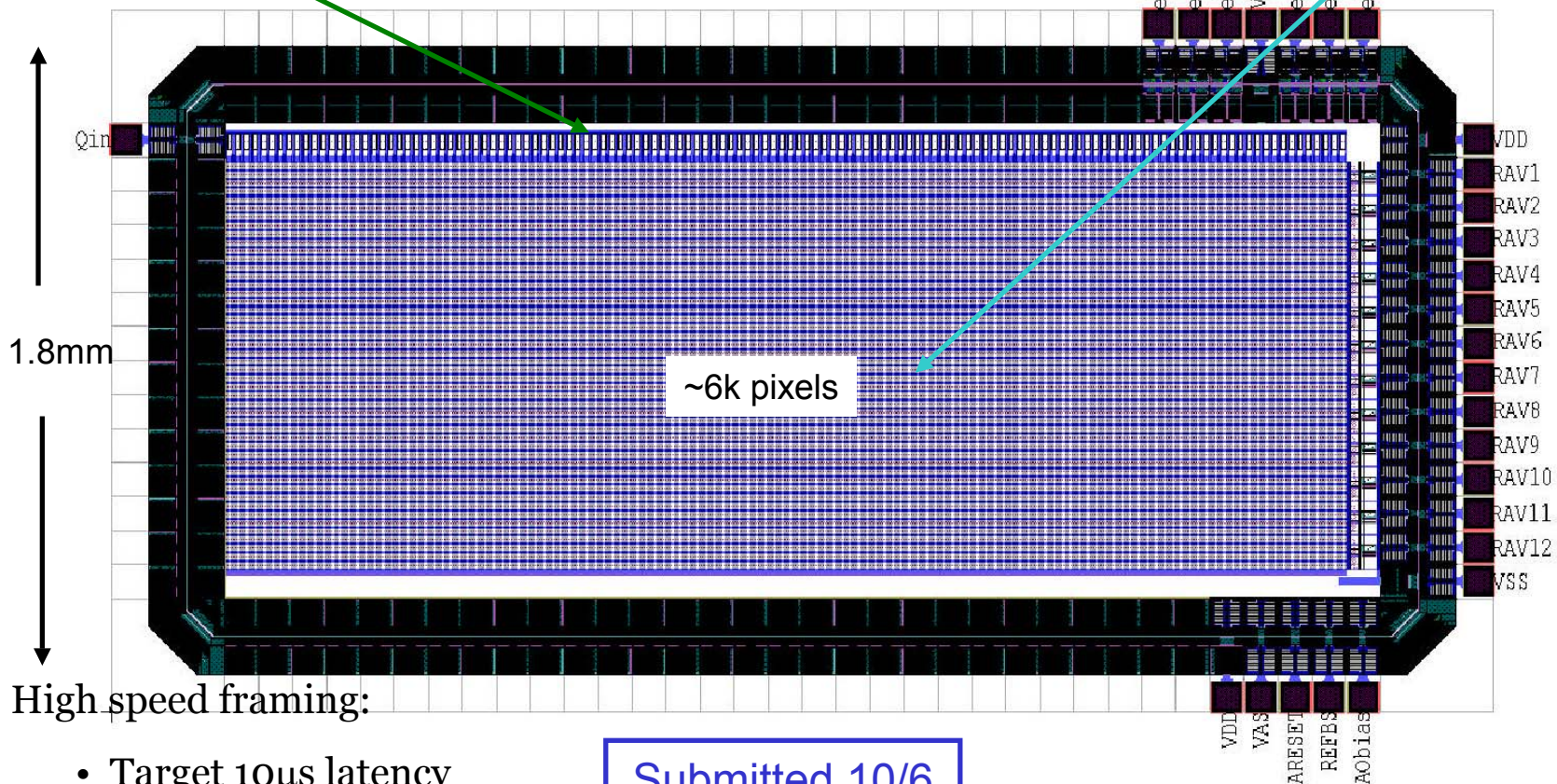


CAP1 Prototype

Column Ctrl Logic

• TSMC 0.35mm Process

132x48 (22.5 μm^2 pixels)



Submitted 10/6
Due back 12/10

“slow” RO resolution $\sim 2\mu\text{m}$

- High speed framing:
 - Target 10 μs latency
- Pipelined readout



CAP2 Concept

- CAP1 architecture difficulties:
 - Significant strain on analog output transfer:
 - * 10ns settling time difficult (will test, but SPICE simulation shows marginal for full-sized detector)
 - Data volume reduction
 - Better if can provide true on-detector pipelining
 - Reduce power if constrict data flow to L1/L2 accepted events (100kHz → 10kHz or 1kHz):
40GSa/s → 4GSa/s or 0.4GSa/s

Possible to put a small pipeline in each pixel?

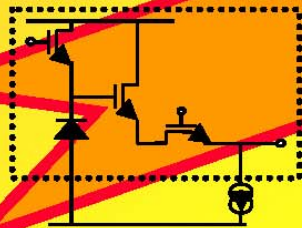


Yes! In fact not unique (RAL)

From PPARC Funding proposal request

Design for science-grade MAPS

Where we come from



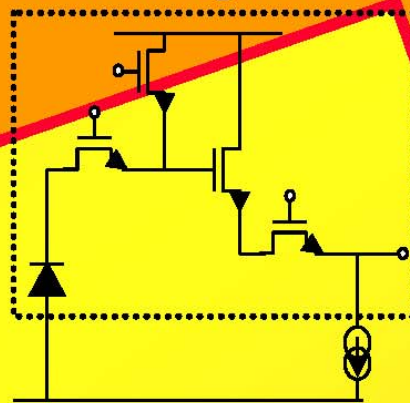
Consumer MAPS.

3 transistors

Simple, but high noise, no data processing, ...

Where we went from 2001 till now

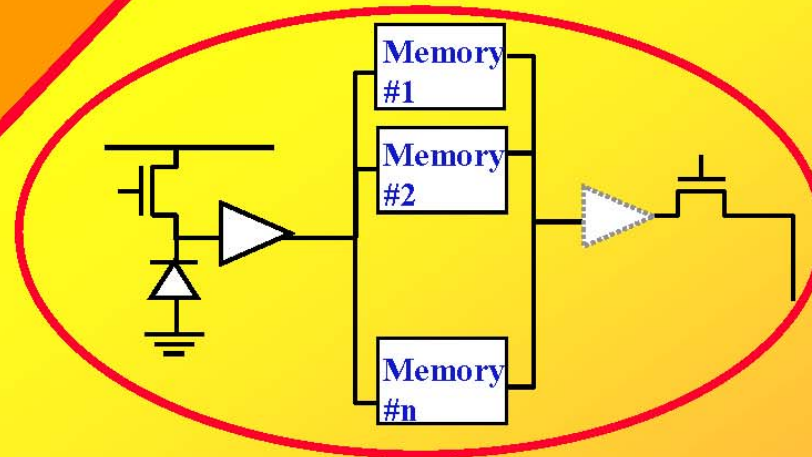
1st science-grade MAPS



4 transistors

Reduce kTC and fixed pattern noise, but still relatively slow and no data processing

Where we want to go
Flexible Active Pixel Sensors

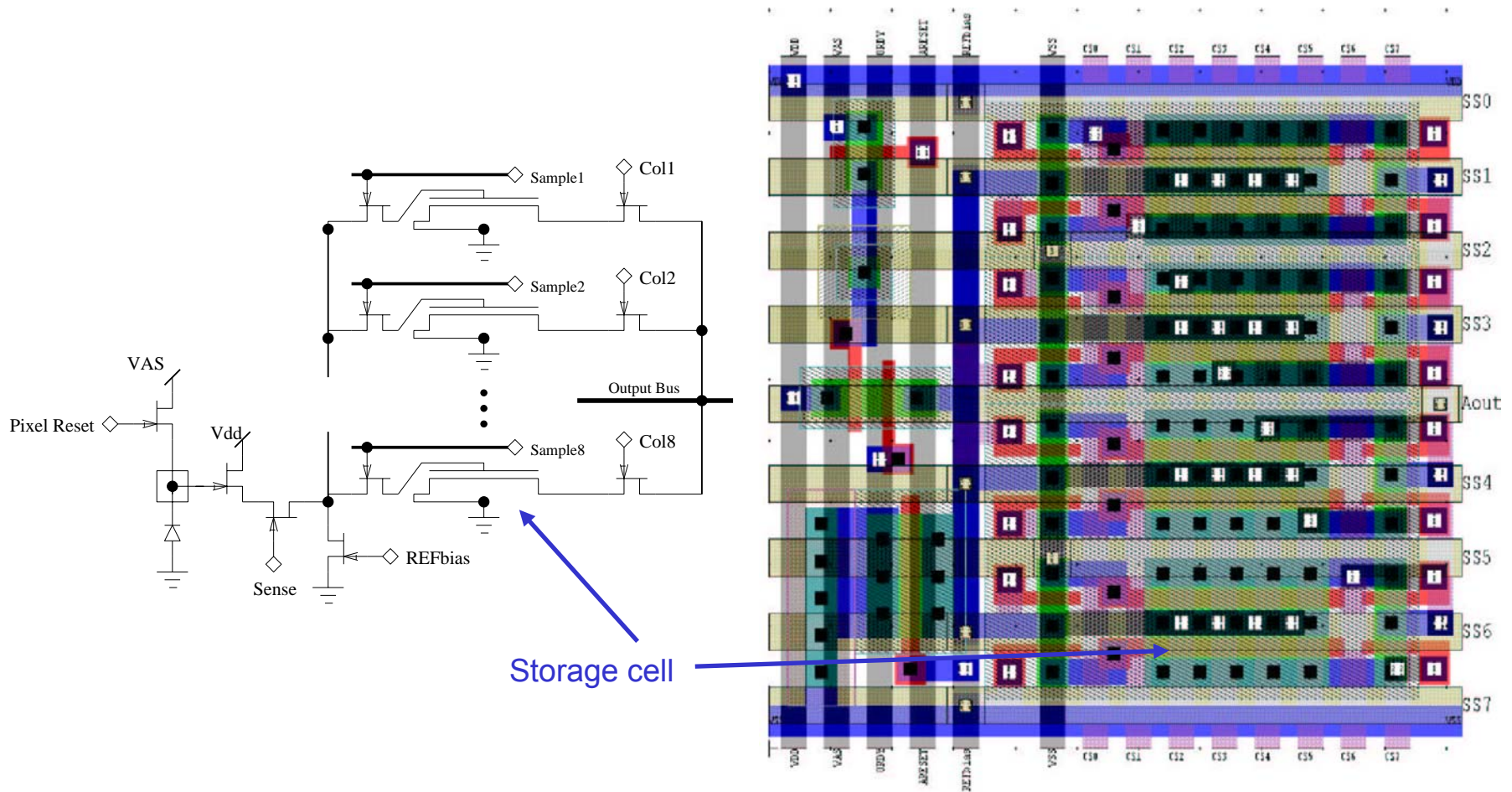


8 transistors + memory cells with storage and selection transistor

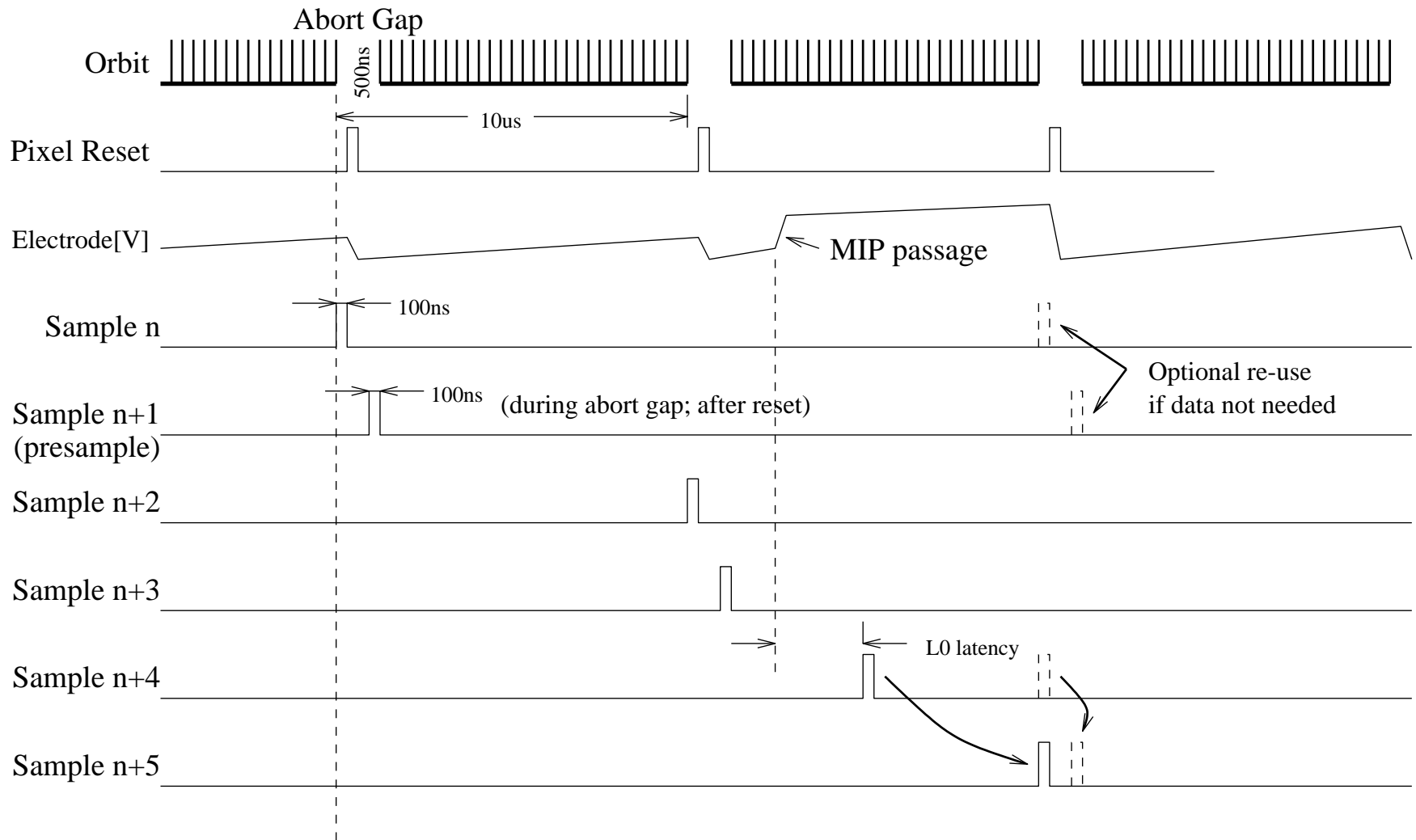
Very high speed, analogue data processing, reduced noise, necessary for particle physics applications



Octal-pipeline (in $22.5\mu\text{m}^2$ pixel)



One Operating Mode

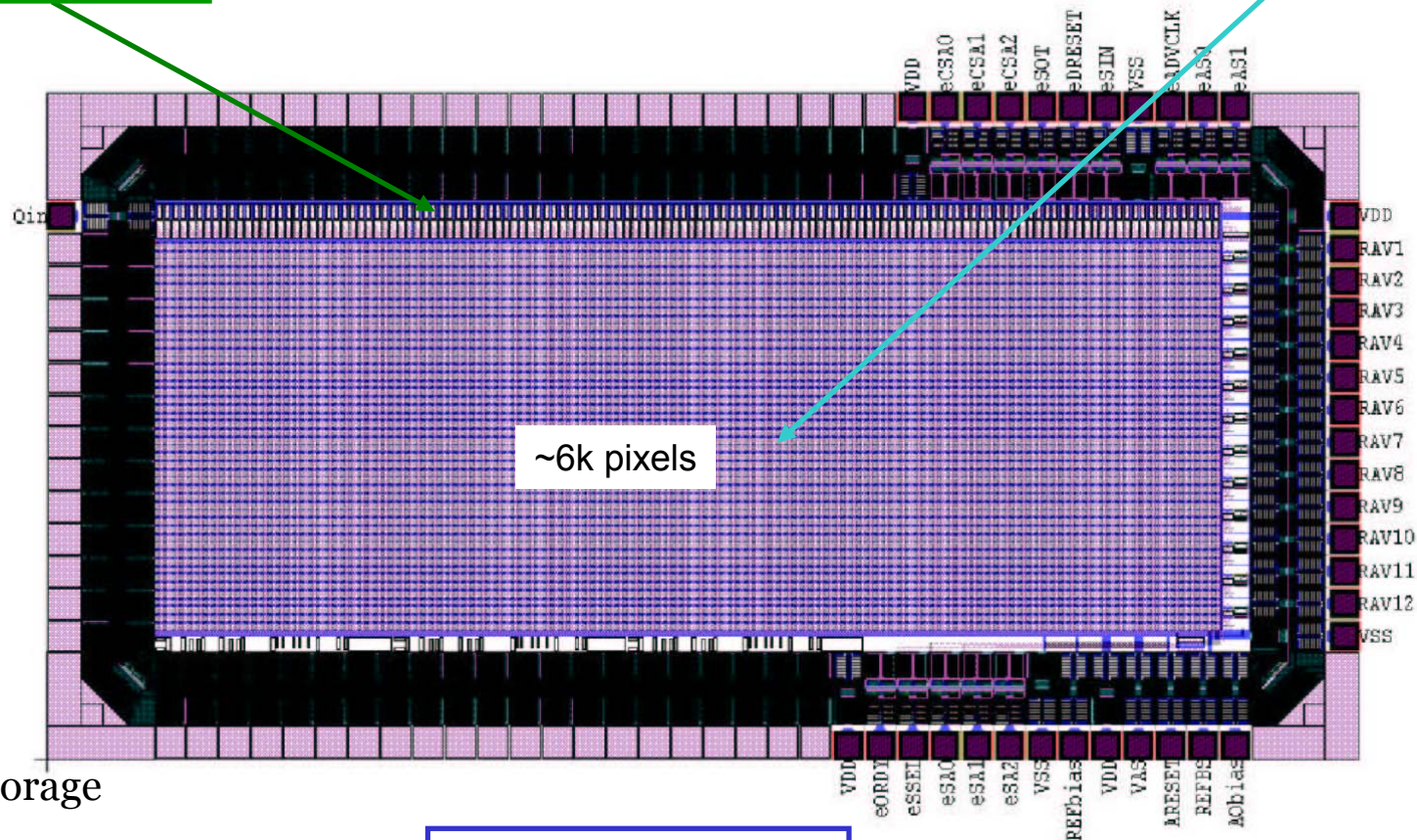


CAP2 Prototype

Column Ctrl Logic

• TSMC 0.35mm Process

132x48 (22.5 μm^2 pixels)



1.8mm

~6k pixels

Submitted 10/27
Due back Jan 10?

“slow” RO resolution $\sim 2\mu\text{m}$

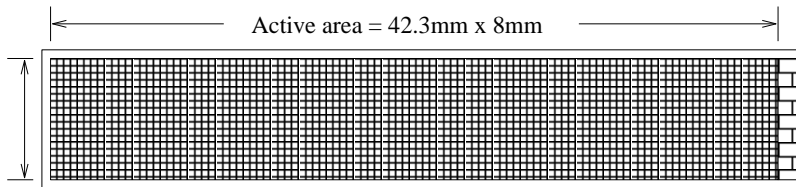
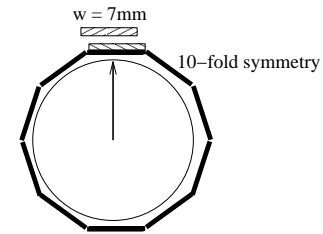
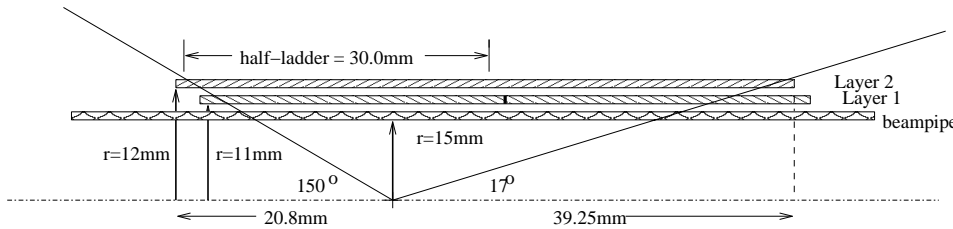
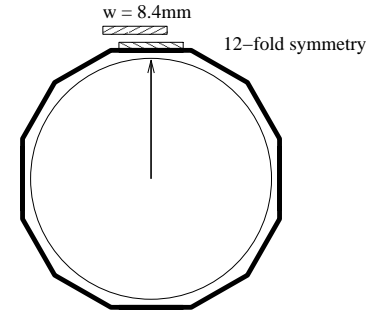
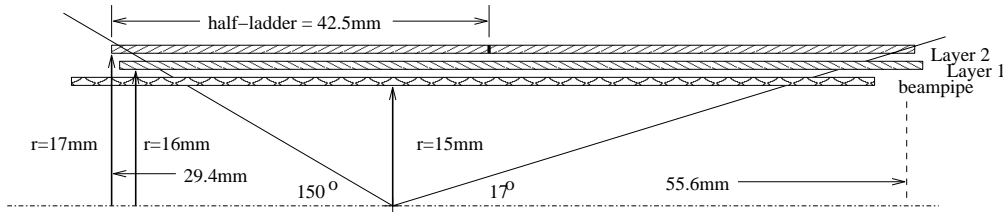
• 8-deep storage

• Target 50 μs latency

• Triggered readout



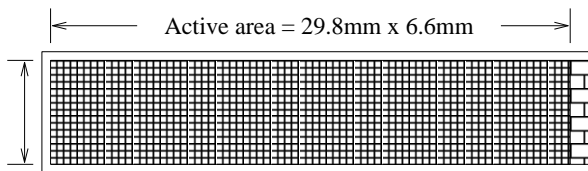
Channel Count



1880 x 356 = 669k channels

2 layers * 24 HL = 32M pixels

Half-ladders:



1324 x 293 = 388k channels

2 layers * 20 HL = 15.5M pixels



Required Transfer Rates

- CAP1 architecture (if $10\mu\text{s}$ max. latency):

- 15mm radius:

- 67 Gpixels/s
- $\sim 1\text{Gpixel/s/pin}$

- 10mm radius

- 39 Gpixels/s
- $\sim 0.5\text{Gpixel/s/pin}$

Two ways around:
Multi-orbit
“Tiling”

- CAP2 architecture ($\geq 100\mu\text{s}$ max. latency):

- 15mm radius:

- 6.7 Gpixels/s
- $\sim 100\text{Mpixel/s/pin}$

- 10mm radius

- 3.9 Gpixels/s
- $\sim 50\text{Mpixel/s/pin}$

Real max. latency
Set by $\langle L1/L2 \rangle$ rate



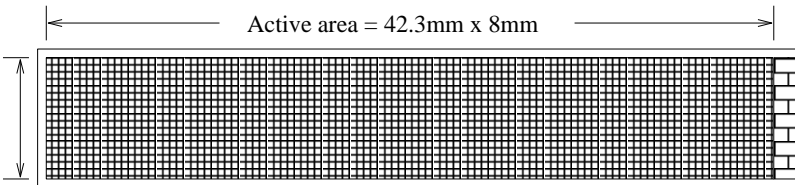
Occupancy Scaling

- Work from following assumptions:
 - Super-B canonical x20 background increase
 - Assume 10% Layer 1 occupancy as “current”
 - Strip area (L1) = 85mm x 50 μ m = 4.25M μ m²
 - Pixel spatial reduction:
 - Pixel area = 22.5 μ m x 22.5 μ m = 506 μ m²
 - Reduction factor ~8400
 - Pixel temporal loss:
 - 0.5 μ s SVD vs. 10 μ s PVD (could be improved)
 - Increase factor ~ 20
 - Grand total:
 - 10% * 20 * 8400⁻¹ * 20
 - Can expect ~ 0.5% occupancy



Event size

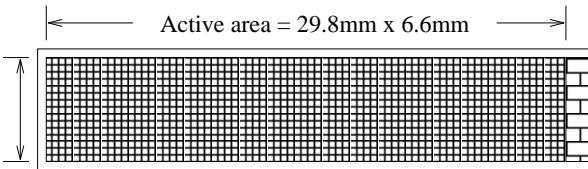
- Conservatively take 1% as Occupancy



1880 x 356 = 669k channels

2 layers * 24 HL = 32M pixels

320k Pixels



1324 x 293 = 388k channels

2 layers * 20 HL = 15.5M pixels

155k Pixels

- 1 Byte/pixel (8bit ADC) sufficient
- **However**, need ~25 bits of address info
- 4 Bytes/pixel → 620-1280kB/event
- Can reduce with clustering/track matching?



The Bottleneck

- Not trivial, but probably possible to:
 - Sample with adequate SNR
 - Read data off pixel with small enough latency
 - Provide periodic analog resets without incurring deadtime
- However:
 - Not easy to get this torrent to the electronics hut
 - Exploring 2 different fiber optics schemes
 - Custom SiGe mixer/modulator may be a solution
- Looks like can fit everything in one COPPER crate:
 - 1 high-speed fiber/half ladder
 - 1 high-speed fiber/FINESSE
 - Each FINESSE does all CDS/offset calculations
 - CPU does clustering?

“Kiseru”?



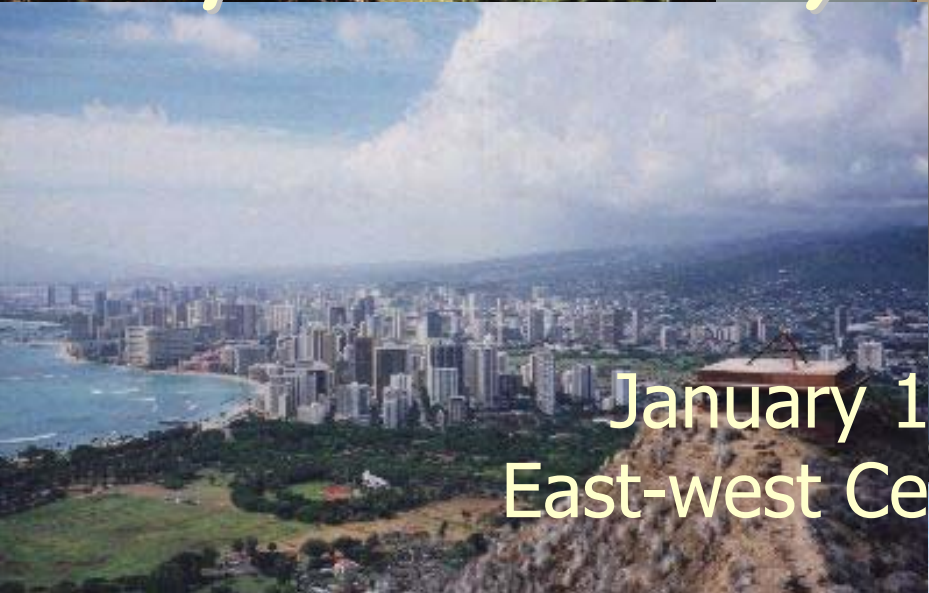
Summary

- Expect serious COPPER work to begin in 2004:
 - 3x FINESSE designs – one of which for *at speed* emulation
 - PID readout prototype electronics?
 - Settle system control issues
- Pixel Plans:
 - 2x prototypes in fab, full-size in 2004 (after beam test)
 - Much effort required on back-end
 - Enormous data volumes
 - Extreme bandwidth
 - Large reduction possible – algorithms?
- Items want to bring up while in Nara:
 - What really sets the max. latency?
 - Any useful pixel info at upper (L3/L4) level?
 - Next discussion: (next slide)

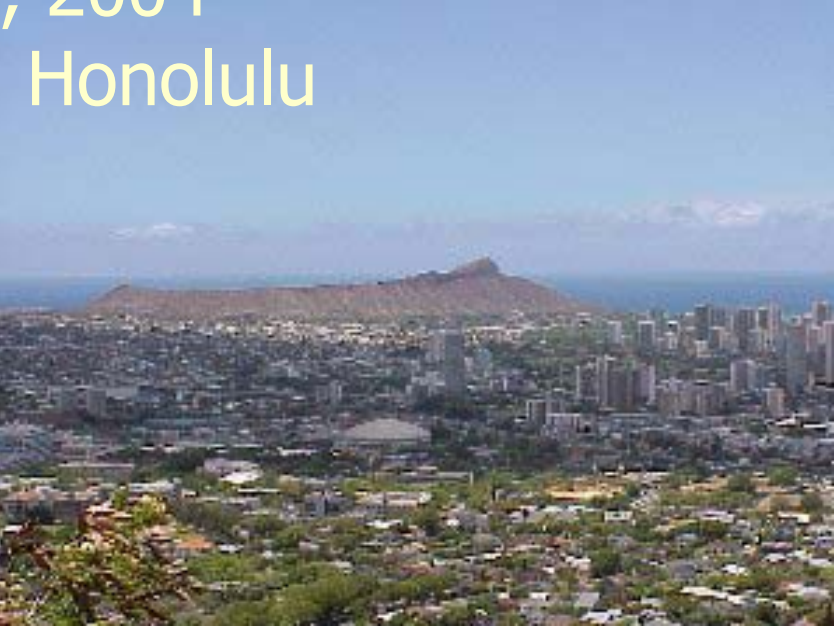




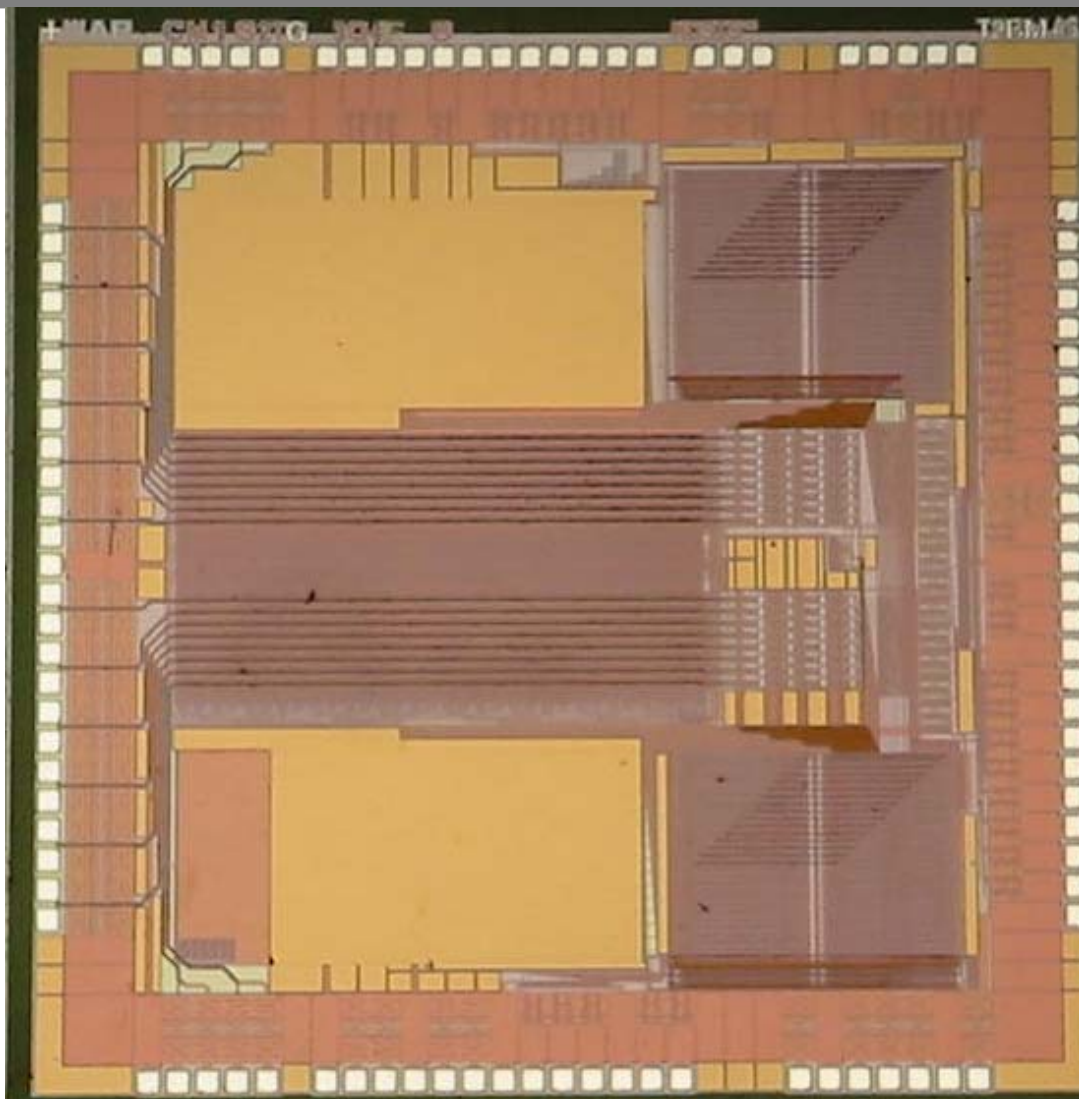
Super B Factory Workshop in Hawaii



January 19-22, 2004
East-west Center, Honolulu



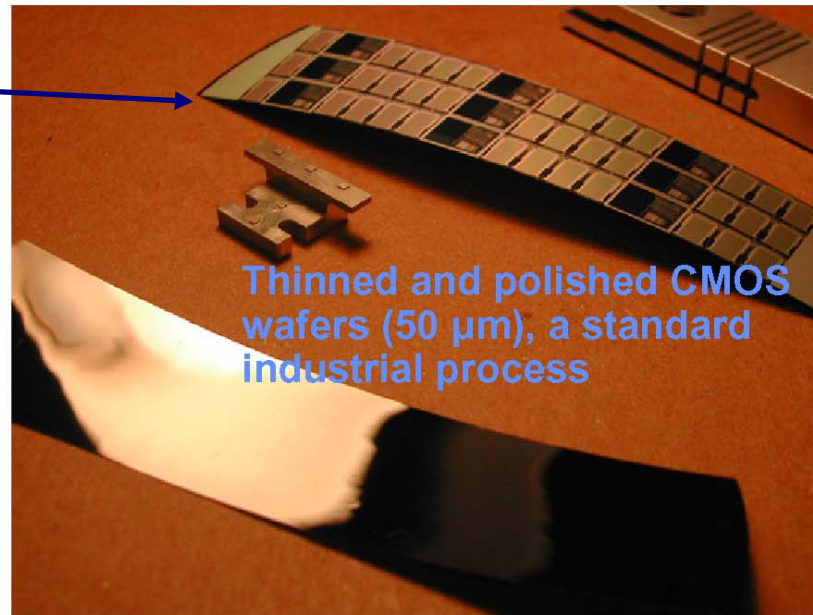
Back-up slides



Thin is In

1. Thinning the substrate to $50\ \mu\text{m}$ (or less)
2. Low mass (air?) cooling: keeping down the power dissipation ($\sim 100\ \text{mW}/\text{cm}^2$)

LBNL old wafer



Thinned and polished CMOS wafers ($50\ \mu\text{m}$), a standard industrial process

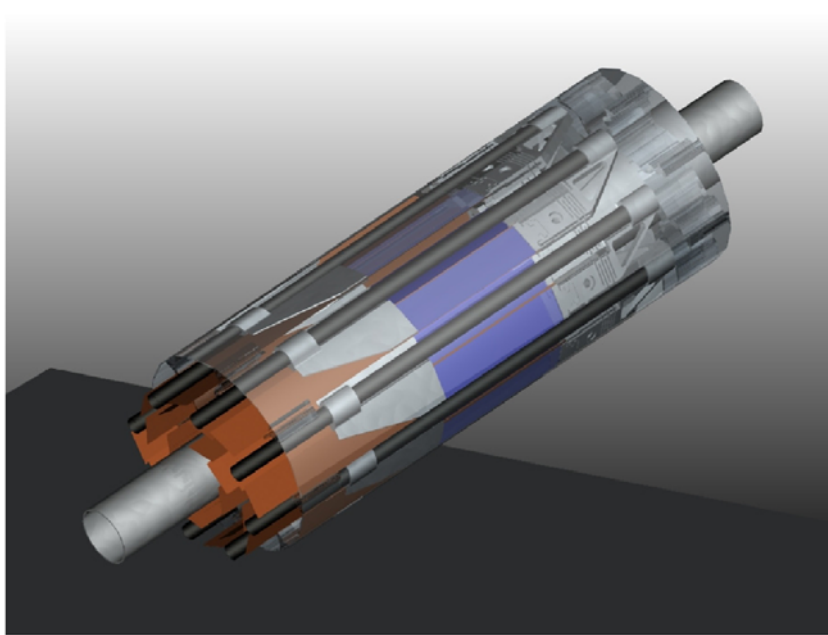
Sample $100\ \mu\text{m}$ Thick wafers from Chris Kenney



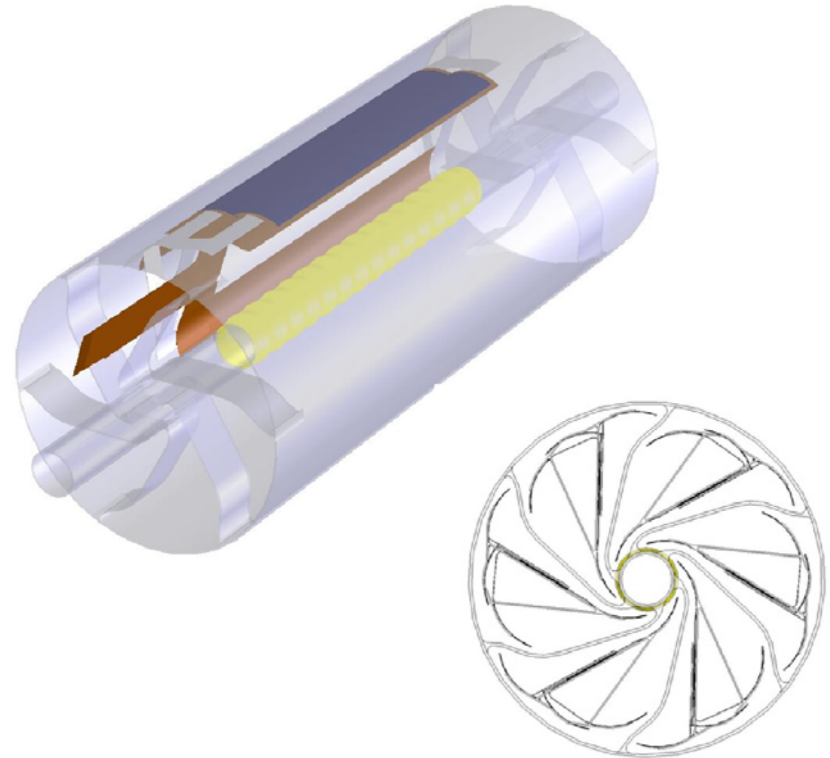
Mechanics

Very preliminary

Mechanical concepts of STAR Micro vertex upgrade using ultra-thin CMOS MAPS *



Tension concept



Self supporting Venetian blade concept

Marc Rosen has some ideas

* Curtsey to Howard Wieman, LBL, STAR group

